

Customer No. 30223

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application Of:
Fujio Kuwako

) Atty. Docket No.: 47163-00018USD1

)

) Examiner: K. Cuneo

)

Group Art Unit: 2841

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Application No.: 09/591,523

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Filed: June 9, 2000

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For: Method for Producing Multi-
Layer Printed Wiring Boards
Having Blind Vias

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CERTIFICATE OF MAILING
37 C.F.R. 1.8I hereby certify that this correspondence is being deposited
with the United States Postal Service as First Class Mail,
postage prepaid, in an envelope addressed to: Commissioner
for Patents, Attn: Box Issue Fee, Washington, D.C. on the
date indicated below:

Date

4/21/03

Signature

Deborah Lick

AMENDMENT UNDER 37 CFR 1.312

Commissioner for Patents
Washington, D.C. 20231
Attn: Box Issue Fee

Dear Sir:

This Amendment is responsive to the Notice of Allowance and Issue Fee Due dated April 8, 2003. Amendment of the claims is respectfully requested in view of the following remarks.

CHICAGO 254596v1 47163-00018USD1